1. (Currently Amended) An arrangement comprising:

a first semiconductor chip configured to transmit load control data and pilot data on a single line;

a second semiconductor chip coupled to the first semiconductor chip and configured to receive the load control data and the pilot data; and

a plurality of electrical loads coupled to the second semiconductor chip;

wherein the second semiconductor chip is configured to:

- a) drive the plurality of electrical loads based on a timing that is defined by the load control data,
- b) transmit to the first semiconductor chip diagnostic data, which represent at least one of a plurality of states of the second semiconductor chip and events which occur in the second semiconductor chip, and
- c) control a transmission rate of the diagnostic data as prescribed by the pilot data.
- 2. (Original) The arrangement as claimed in claim 1, wherein the first semiconductor chip is a program-controlled unit.
- 3. (Original) The arrangement as claimed in claim 1 wherein the second semiconductor chip is a power chip.
- 4. (Previously Presented) The arrangement as claimed in claim 1, wherein the diagnostic data are

Application No. 10/727,108

Amendment dated November 18, 2008

Reply to Office Action of August 18, 2008

transmitted in time with a transmission clock signal generated in the second semiconductor chip,

and the transmission clock signal is not transmitted to the first semiconductor chip.

5. (Previously Presented) The arrangement as claimed in claim 1, wherein the transmission rate is

prescribed by transmitting a division factor, and the second semiconductor chip divides the

frequency of a transmission clock signal received from the first semiconductor chip by the division

factor, and transmits the diagnostic data to the first semiconductor chip in time with the resultant

transmission signal.

6. (Previously Presented) The arrangement as claimed in claim 5, wherein the transmission clock

signal transmitted to the second semiconductor chip represents the transmission clock which is used

by the first semiconductor chip to transmit the load control data or the pilot data to the second

semiconductor chip.

7. (Previously Presented) The arrangement as claimed in claim 6, wherein the diagnostic data are

transmitted in units of frames and each frame starts with a start bit having a prescribed value and

ends with one or two stop bits having prescribed values.

8. (Previously Presented) The arrangement as claimed in claim 1, wherein the first semiconductor

chip ascertains a phase of the diagnostic data by oversampling the diagnostic data.

9. (Previously Presented) The arrangement as claimed in claim 1, wherein the diagnostic data are

transmitted via a line, which transmits neither the load control data nor the pilot data.

10. (Original) The arrangement as claimed in claim 1, wherein the load control data and the pilot

data are transmitted via a transmission channel.

11. (Previously Presented) The arrangement as claimed in claim 10, wherein the transmission

channel comprises:

3

DOCSNY-337949v01

Docket No.: J0658.0006

a transmission clock line via which the first semiconductor chip transmits a transmission clock

signal to the second semiconductor chip;

a data line via which the first semiconductor chip transmits the load control data and the pilot data

to the second semiconductor chip in time with the transmission clock signal; and

a chip select line via which the first semiconductor chip transmits a chip select signal to the second

semiconductor chip,

wherein said chip select signal indicates to the second semiconductor chip a start and end of data

transmission intended for the second semiconductor chip via the data line.

12. (Previously Presented) The arrangement as claimed in claim 1, wherein the load control data

and the pilot data are transmitted in units of frames and are transmitted using time-division

multiplexing.

13. (Previously Presented) The arrangement as claimed in claim 12, wherein the first

semiconductor chip defines time windows of constant length and transmits in each time window

either a load control data frame or a pilot data frame or no data.

14. (Previously Presented) The arrangement as claimed in claim 13, wherein the first

semiconductor chip transmits no further load control data frames for a respective length of n time

windows after transmission of a load control data frame,

wherein $n \ge 0$ and n can be set by a user of the arrangement.

15. (Previously Presented) The arrangement as claimed in claim 14, wherein a pilot data frame can

be transmitted only in a time window in which no load control data frame is transmitted.

4

DOCSNY-337949v01

Docket No.: J0658.0006

16. (Original) The arrangement as claimed in claim 13, wherein transmission of the pilot data has

priority when load control data and pilot data are awaiting transmission simultaneously.

17. (Previously Presented) An arrangement comprising

a first semiconductor chip and a second semiconductor chip connected thereto,

where the second semiconductor chip is additionally connected to electrical loads and drives these

electrical loads on the basis of a timing which is defined by load control data,

where the first semiconductor chip transmits via a transmission channel to the second

semiconductor chip the load control data and pilot data which control the second

semiconductor chip,

where the transmission channel comprises:

a first transmission clock line via which the first semiconductor chip transmits a

transmission clock signal to the second semiconductor chip;

a second transmission clock line via which the first semiconductor chip transmits an inverse

of the transmission clock signal to the second semiconductor chip;

a first data line via which the first semiconductor chip transmits the load control data and the

pilot data to the second semiconductor chip in time with the transmission clock

signal;

a second data line via which the first semiconductor chip transmits an inverse of the load

control data and an inverse of the pilot data to the second semiconductor chip; and

a chip select line via which the first semiconductor chip transmits a chip select signal to the

5

second semiconductor chip,

wherein said chip select signal signals to the second semiconductor chip a start and end of

transmission of data intended for the second semiconductor chip via the data line,

where the second semiconductor chip transmits to the first semiconductor chip diagnostic data

which represent at least one of states prevailing in the second semiconductor chip and events

which occur in the second semiconductor chip,

wherein the first semiconductor chip includes means for transmitting appropriate pilot data to the

second semiconductor chip, and the second semiconductor chip includes means for

controlling a transmission rate by which the diagnostic data is transmitted to the first

semiconductor chip in accordance with the appropriate pilot data.

18. (Previously Presented) The arrangement as claimed in claim 17, wherein output drivers on the

first semiconductor chip, which output the load control data, the pilot data and the transmission

clock signal, are LVDS drivers or other special drivers whose use allows electromagnetic

interference to be kept down.

19. (Previously Presented) The arrangement as claimed in claim 1, wherein the first semiconductor

chip has a plurality of output drivers configured to output the load control data, the pilot data and

the transmission clock signal.

20. (Previously Presented) The arrangement as claimed in claim 17, wherein output drivers on the

first semiconductor chip, which output the load control data, the pilot data and the transmission

clock signal, are special drivers configured to minimize electromagnetic interference.

6

DOCSNY-337949v01